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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

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**Superabrasive products-Precision grinding wheels for
semiconductor wafers**

超硬磨料制品 半导体晶圆精密磨削用砂轮

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Table of Contents

Preface	III
1 Scope	1
2 Normative references	1
3 Terms and Definitions	1
4 Product Categories	1
4.1 Grinding wheels for precision grinding of wafer edge chamfering (hereinafter referred to as "chamfering grinding wheels")	1
4.2 Grinding wheels for wafer end surface thinning precision grinding (hereinafter referred to as "thinning grinding wheels")	3
5 Product Marking	12
5.1 Chamfering grinding wheel	12
5.2 Thinning grinding wheel	12
6 Technical Requirements	12
6.1 Appearance	12
6.2 Limit deviations of basic dimensions	13
6.3 Geometric tolerances	15
6.4 Matrix roughness	15
6.5 Dynamic balancing	15
6.6 Rotational strength	15
7 Test methods	15
7.1 Appearance	15
7.2 Basic size	16
7.3 Geometric tolerances	16
7.4 Matrix roughness	17
7.5 Dynamic balancing	17
7.6 Rotational strength	17
8 Inspection rules	17
9 Sign	17
9.1 Product Labelling	17
9.2 Certificate of Conformity	17
9.3 Outer packaging marking	17
10 Packaging, transportation and storage	18
10.1 Packaging	18

10.2 Transportation	18
10.3 Storage	18

Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

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1 Scope

This document specifies the product classification, product marking, technical requirements, test methods, inspection rules, Labeling, packaging, transportation and storage.

This document applies to metal bonds, resin bonds and ceramic bonds used for precision grinding of semiconductor wafer edge chamfering and end face thinning.

Diamond grinding wheels with porcelain bond and composite bond.

2 Normative references

GB/T 1800.2-2020

GB/T 2493

GB/T 9239.1

GB/T 16458

GB/T 35479

3 Terms and definitions

The terms and definitions defined in GB/T 16458 apply to this document.

4 Product Categories

4.1 Grinding wheel for precision grinding of wafer edge chamfering (hereinafter referred to as "chamfering grinding wheel")

4.1.1 Abrasive layer groove type

The groove type and code of the abrasive layer are shown in Table 1.